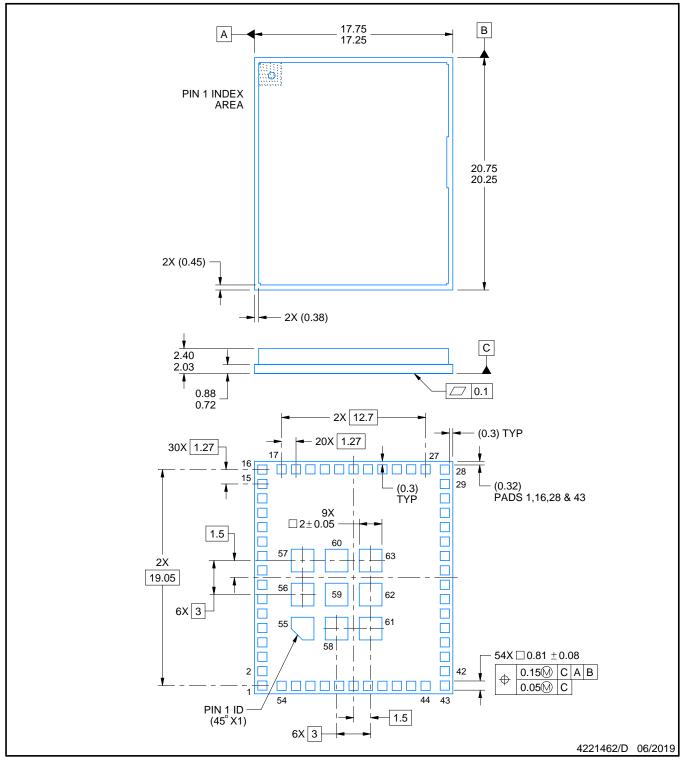
MOB0063A



PACKAGE OUTLINE

QFM - 2.4 mm max height

QUAD FLAT MODULE



NOTES:

- 1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M. 2. This drawing is subject to change without notice.

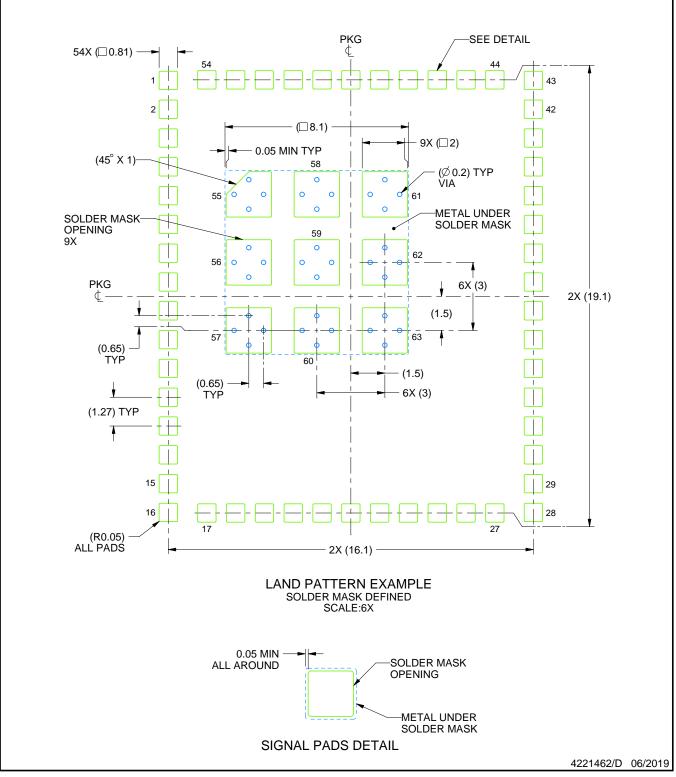


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EXAMPLE BOARD LAYOUT

QFM - 2.4 mm max height

QUAD FLAT MODULE



NOTES: (continued)

3. This package is designed to be soldered to a thermal pad on the board. For more information, see Texas Instruments literature number SLUA271 (www.ti.com/lit/slua271).

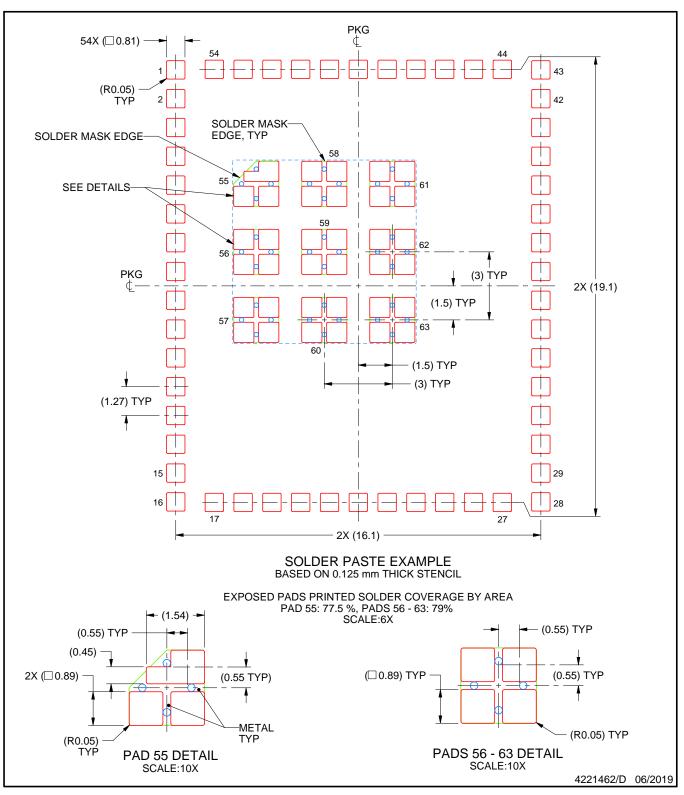


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EXAMPLE STENCIL DESIGN

QFM - 2.4 mm max height

QUAD FLAT MODULE



NOTES: (continued)

4. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.



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